

ELECTRICAL CIRCUIT APPARATUS AND METHOD FOR ASSEMBLING SAME

ABSTRACT OF THE DISCLOSURE

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An electrical circuit apparatus (300) that includes: a substrate (330) having a ground layer (336), at least one device aperture (332), and at least one solder aperture (334); a heat sink (310); and an adhesive layer (320) for mechanically coupling the heat sink to the ground layer of the substrate such that at least a portion of the substrate device aperture overlaps the heat sink, the adhesive layer having at least one device aperture and at least one solder aperture, wherein aligning the at least one substrate solder aperture with the at least one adhesive layer solder aperture and aligning the at least one substrate device aperture with the at least one adhesive layer device aperture enables solder wetting in a predetermined area between the heat sink and the ground layer of the substrate.

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